



Material Content Data Sheet



Sales Product Name				IAUA200N04S5N010		Issued		4. March 2019	
MA#				MA001819654					
Package				PG-HSOF-5-1		Weight*		368.85 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.610	0.44	0.44	4366	4366	
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.00		39		
	non noble metal	iron	7439-89-6	0.048	0.01		131		
	non noble metal	copper	7440-50-8	48.418	13.13	13.14	131269	131439	
	noble metal	gold	7440-57-5	0.040	0.01	0.01	109	109	
encapsulation	organic material	carbon black	1333-86-4	2.127	0.58		5767		
	plastics	epoxy resin	-	23.400	6.34		63441		
	inorganic material	silicondioxide	60676-86-0	116.289	31.53	38.45	315280	384488	
leadfinish	non noble metal	tin	7440-31-5	3.673	1.00	1.00	9958	9958	
plating	noble metal	silver	7440-22-4	0.015	0.00	0.00	41	41	
solder	non noble metal	tin	7440-31-5	0.043	0.01		115		
	noble metal	silver	7440-22-4	0.053	0.01		144		
	non noble metal	lead	7439-92-1	2.030	0.55	0.57	5503	5762	
heatspreader	inorganic material	phosphorus	7723-14-0	0.043	0.01		116		
	non noble metal	iron	7439-89-6	0.143	0.04		387		
	non noble metal	copper	7440-50-8	142.638	38.68	38.73	386714	387217	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.008	0.00		23		
	non noble metal	iron	7439-89-6	0.028	0.01		77		
	non noble metal	copper	7440-50-8	28.224	7.65	7.66	76520	76620	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com